

Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) A liquid crystal ~~device~~ device, comprising:
_____ a pair of substrates;
_____ a liquid crystal layer provided ~~therebetween~~ the pair of substrates; and
_____ a sealing material bonding ~~said~~ the pair of substrates to each other and enclosing the liquid crystal layer between ~~said~~ the pair of substrates,
_____ ~~wherein~~ the sealing material ~~contains~~ containing a photocurable component and a thermosetting component, the photocurable component ~~has~~ having a maximum curing rate in the range of from 60% to 95%, and the thermosetting component ~~has~~ having a curing rate in the range of from 60% to 90%.
2. (Currently Amended) The liquid crystal device according to Claim 1, ~~wherein~~ the sealing material ~~comprises~~ including a resin containing the photocurable component and the thermosetting component in the same molecular chain.
3. (Currently Amended) The liquid crystal device according to Claim 1, ~~wherein~~ the sealing material ~~comprises~~ including a resin containing the photocurable component, a resin containing the thermosetting component, and a resin containing the photocurable component and the thermosetting component in the same molecular chain.
4. (Currently Amended) The liquid crystal device according to Claim 1, ~~wherein~~ the photocurable component ~~comprises~~ including at least one of an acrylic group and/or a methacrylic group.
5. (Currently Amended) The liquid crystal device according to Claim 1, ~~wherein~~ the thermosetting component ~~comprises~~ including an epoxy group.

6. (Currently Amended) A method for manufacturing a liquid crystal device having a liquid crystal layer provided between a pair of substrates, the method comprising:

- ~~a step of~~ applying an adhesive onto at least one of surfaces of ~~said the~~ pair of substrates to form a closed frame shape in a region of the surface thereof;
- ~~a step of~~ disposing spacers on at least one of surfaces of ~~said the~~ pair of substrates;
- ~~a step of~~ dripping liquid crystal onto at least one of surfaces of ~~said the~~ pair of substrates after the adhesive and the spacers are disposed;
- ~~a step of~~ bonding ~~said the~~ pair of substrates to each other after the liquid crystal is dripped; and
- ~~a step of~~ curing the adhesive after the bonding is performed,

~~wherein the adhesive is being~~ an uncured material which is formed to a sealing material according to Claim 1 by curing, the sealing material containing a photocurable component and a thermosetting component, the photocurable component having a maximum curing rate in the range of from 60% to 95%, and the thermosetting component having a curing rate in the range of from 60% to 90%.

7. (Currently Amended) A method for manufacturing a liquid crystal device having a liquid crystal layer provided between a pair of substrates, the method comprising:

- ~~a step of~~ applying an adhesive onto at least one of surfaces of ~~said the~~ pair of substrates to form a frame shape provided with a liquid crystal inlet;
- ~~a step of~~ disposing spacers on at least one of surfaces of ~~said the~~ pair of substrates;
- ~~a step of~~ bonding ~~said the~~ pair of substrates to each other after the adhesive and the spacers are disposed;
- ~~a step of~~ curing the adhesive after the bonding is ~~performed, performed;~~ and

~~a step of injecting liquid crystal inside the adhesive through the liquid crystal inlet; inlet,~~

~~_____ wherein the adhesive is being an uncured material which is formed to a sealing material according to Claim 1 by curing. curing, the sealing material containing a photocurable component and a thermosetting component, the photocurable component having a maximum curing rate in the range of from 60% to 95%, and the thermosetting component having a curing rate in the range of from 60% to 90%.~~

8. (Currently Amended) The method for manufacturing a liquid crystal ~~device, device~~ according to Claim 6, ~~wherein the step of curing of the adhesive comprises including~~ a light irradiation substep of curing the photocurable component, and the amount of light irradiation in the light irradiation substep ~~is being~~ 1,000 to 6,000 mJ/cm².

9. (Currently Amended) The method for manufacturing a liquid crystal ~~device, device~~ according to Claim 6, ~~wherein the step of curing of the adhesive comprises including~~ a heating substep of curing the thermosetting component, and the heating temperature and the heating time in the heating substep ~~are being~~ set to 60 to 160°C and 20 to 300 minutes, respectively.

10. (Currently Amended) An electronic ~~apparatus-apparatus, comprising~~ ~~acomprising:~~
~~_____ the liquid crystal device according to Claim 1.~~